

WHAT IS CLAIMED IS:

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- A method for forming a moisture reactive hot melt adhesive comprising
- a) forming a hydroxyl-functional prepolymer by reacting first components comprising a polyol selected from the group consisting of polyether polyols, polyester polyols, and mixtures thereof and a polyisocyanate, the ratio of OH/NCO groups of said first components on an equivalents basis being from 1.05 to 3.0;
 - b) admixing second components comprising said hydroxyl-functional prepolymer, a polyol selected from the group consisting of polyether polyols, polyester polyols, and mixtures thereof, and a polyisocyanate, the weight ratio of said hydroxyl-functional prepolymer to said polyol being from 9/1 to 1/9, and the ratio of NCO/OH groups of said second components on an equivalents basis being from 1.5 to 2.2; and
 - c) reacting, or allowing to react, said admixture.
2. The method of claim 1 wherein said second components comprise said hydroxyl-functional prepolymer, a crystalline polyester polyol, and a polyisocyanate, the weight ratio of said hydroxyl-functional prepolymer to said polyol being from 9/1 to 1/9, and the ratio of NCO/OH groups of said second components on an equivalents basis being from 1.5 to 2.2.
3. A moisture reactive hot melt adhesive formed by the method of claim 1 or claim 2.
- 25 4. A method for bonding substrates comprising forming a moisture reactive hot melt adhesive by the method of claim 1 or claim 2;
- heating said hot melt adhesive to a temperature of 90 °C to 140 °C ;
- 30 applying said heated hot melt adhesive to a first substrate in the presence of moisture;

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contacting said applied heated hot melt adhesive with a second substrate;
cooling, or allowing to cool, said adhesive.